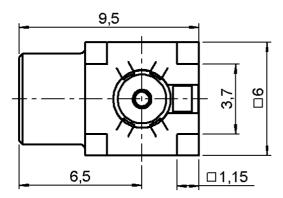
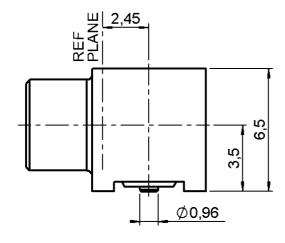
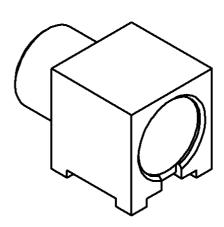
R113.664.000

Series: MCX









All dimensions are in mm.

			~ ~	
_	COMPONENTS	MATERIALS	PLATINGS (µm)	
	BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2	
		1	I	

Issue: 0420 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



R113.664.000

Series: MCX

PACKAGING

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50Ω Frequency 0-6 GHz

Frequency **0-6** GHz VSWR **1.25** + **0.000** x F(0)

VSWR 1.25 + 0.000 x F(GHz) Maxi Insertion loss 0.03 $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (NA - F(GHz)) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 1000 Veff mini 1000 M Ω mini

ENVIRONMENTAL

Operating temperature -55/+155 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction NA

Others:

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **1.640** g

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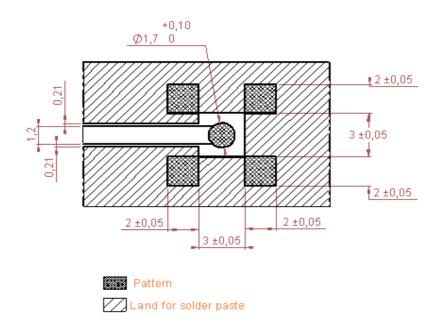


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Series: MCX

MCX SERIES - INFORMATION

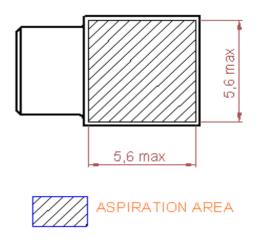
Coplanar line : pattern and signal are on the same side . Thickness of PCB :.063(1.6mm) The material of PCB is the epoxy resin of glass fabrics bacs . (Er = 4.8) . The solder resist should be printed exept for the land pattern on the PCB .



SHADOW OF MCX RECEPTACLE FOR VIDEO CAMERA

6.05 6.05 9.625

ASPIRATION AREA



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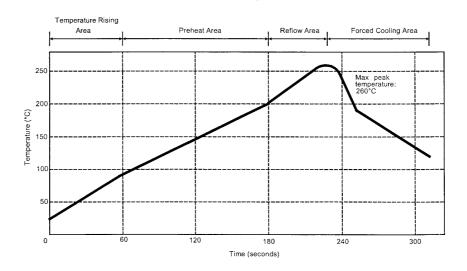
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Series: MCX

SOLDER PROCEDURE

- 1. Deposit solder paste 'Sn Ag4 Cu0.5" on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 Video camera is preferred to check the positioning of the compnent. Adhesive agents are forbidden on the receptacle.
- 3. Soldering by infra-red reflow.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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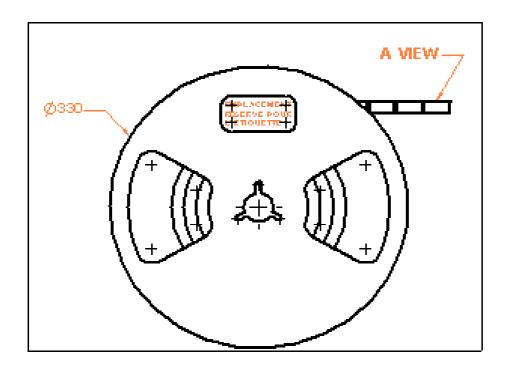
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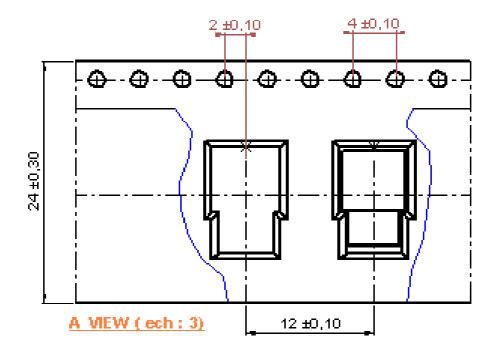




R113.664.000

Series: MCX





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